QFN

BCC/MLF/MLP/LPCC



MECHANICAL PROPERTIES

• Mounting Method to Board

· Socket Operation

• Operating Temperature

re -50° C to

PPS

DoCu

- Contact Force
- Life Cycles

Clamshell lid; ZIF Open Top -50° C to +150° C 30 +/- 5 gf 5,000 Mechanical Cycles

Thru-hole Mount

PHYSICAL PROPERTIES

- · Plastic Body
- · Contact Base Metal
- Contact Plating
- Center Pin Base Metal
- Center Pin Plating
- Springs, Torsion/Coil

Beuu	
Au over Ni; NiB op	tional
Brass; Cu optional	
Au; NiB optional	
Passivated S.S.	

< 50 m0hms

ELECTRICAL PROPERTIES

- · Contact Resistance
- Inductance
- Current Rating
- Volume Resistivity
- Insulation Resistance

3 nH .5A with 30°C rise, 1.0A with 75°C rise 1 x 10^{15} Ohm-cm

560 V/mil

PRODUCT DESCRIPTION

Plastronics has taken a leadership role in designing and developing socket solutions for the newest QFN packages such as MLF, BCC and LPCC. These sockets offer a modular design in a small outline with very low inductance. The new Open Top QFN socket allows for more convenient package loading and unloading in most of the same lead count options as the lidded version.

SPECIFICATIONS (mm)

Available in .40, .50, .65, .80 and 1.00 mm pitches Custom pitches down to .30 mm Lidded and Open Top Sockets for ≤ 10 mm packages Lidded Sockets for 10 - 16 mm packages Center ground pin standard for all sockets Optional copper heat slug available for high wattage devices Sockets for over 80 different JEDEC standard footprints

CONTACT TECHNOLOGY







QFN OFFERINGS

Plastronics offers over 140 QFN socket options. For a complete list, please visit our website at www.PlastronicsUSA.com.



LIDDED BODY SIZE ≤10 mm







OPEN TOP BODY SIZE ≤10 mm





All units in mm unless otherwise noted.



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